SCAS208A - JUNE 1992 - REVISED APRIL 1996

- **Members of the Texas Instruments** Widebus™ Family
- Inputs Are TTL-Voltage Compatible
- Flow-Through Architecture Optimizes **PCB Layout**
- Distributed V_{CC} and GND Pin Configuration **Minimizes High-Speed Switching Noise**
- **EPIC™** (Enhanced-Performance Implanted CMOS) 1-µm Process
- 500-mA Typical Latch-Up Immunity at 125°C
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) Packages Using 25-mil Center-to-Center Pin Spacings and 380-mil Fine-Pitch Ceramic Flat (WD) Packages Using 25-mil Center-to-Center Pin Spacings

description

The 'ACT16541 are noninverting 16-bit buffers composed of two 8-bit sections with separate output-enable signals. For either 8-bit buffer section, the two output-enable $(1\overline{OE1}$ and $1\overline{OE2}$ or 20E1 and 20E2) inputs must both be low for the corresponding Y outputs to be active. If either output-enable input is high, the outputs of that 8-bit buffer section are in the high-impedance state.

54ACT16541...WD PACKAGE 74ACT16541 . . . DL PACKAGE (TOP VIEW)

		_		1
1 0E 1	d 1	\cup	48	1 0 E2
1Y1	2		47]1A1
1Y2	[]3		46]1A2
GND	4		45	GND
1Y3	5		44]1A3
1Y4	6		43]1A4
V_{CC}	7		42]v _{cc}
1Y5] 1A5
1Y6	9]1A6
GND	10			GND
1Y7	_		38] 1A7
1Y8	12		37] 1A8
2Y1	13]2A1
2Y2			35	2A2
GND	15		34	GND
2Y3	16		33]2A3
2Y4				2A4
V_{CC}			31]v _{cc}
2Y5				2A5
2Y6				2A6
GND	_			GND
2Y7	_			2A7
2Y8				2 <u>A8</u>
20E1	24		25	20E2
	_			l

The 74ACT16541 is packaged in TI's shrink small-outline package, which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The 54ACT16541 is characterized for operation over the full military temperature range of -55°C to 125°C. The 74ACT16541 is characterized for operation from -40°C to 85°C.

FUNCTION TABLE (each 8-bit section)

	INPUTS	ОИТРИТ	
OE1	OE2	Α	Y
L	L	L	L
L	L	Н	Н
Н	X	Χ	Z
X	Н	Χ	Z

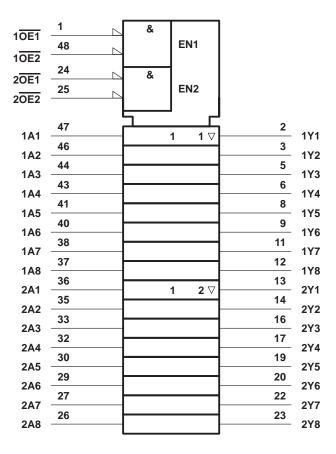


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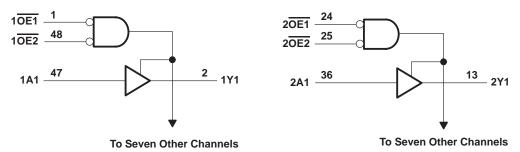


logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)





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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	–0.5 V to 7 V
Input voltage range, V _I (see Note 1)($0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Output voltage range, V _O (see Note 1)($0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$)	±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)	±50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±50 mA
Continuous current through V _{CC} or GND	±400 mA
Maximum package power dissipation at T _A = 55°C (in still air) (see Note 2): DL package	1.2 W
Storage temperature range, T _{stq}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions (see Note 3)

		54ACT16541 MIN NOM MAX		41	74	ACT1654	11	UNIT
				MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2		7	2			V
V _{IL}	Low-level input voltage		Š	0.8			0.8	V
٧ _I	Input voltage	0	200	VCC	0		VCC	V
Vo	Output voltage	0	1	VCC	0		VCC	V
loh	High-level output current		3	-24			-24	mA
loL	Low-level output current	, O.	7	24			24	mA
Δt/Δν	Input transition rise or fall rate	8		10	0		10	ns/V
TA	Operating free-air temperature	-55		125	-40		85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

^{2.} The maximum package power dissipation is calculated using a junction temperature of 150 °C and a board trace length of 750 mils.

54ACT16541, 74ACT16541 16-BIT BUFFERS/DRIVERS WITH 3-STATE OUPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	Vaa	T,	_Δ = 25°C		54ACT	16541	74ACT	16541	UNIT
PARAMETER	TEST CONDITIONS	Vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
	Jour - 50 m	4.5 V	4.4			4.4		4.4		
	IOH = -50 μA	5.5 V	5.4			5.4		5.4		
Voн	10.1 - 24 mA	5.5 V	3.9			3.8		3.8		V
	I _{OH} = -24 mA	5.5 V	4.94			4.8		4.8		
	I _{OH} = -75 mA [†]	5.5 V				3.85		3.85		
	lo 50 uA	4.5 V			0.1		0.1		0.1	
	I _{OL} = 50 μA	5.5 V			0.1		0.1		0.1	
VOL	le: - 24 mA	4.5 V			0.36	4	0.44		0.44	V
	I _{OL} = 24 mA	5.5 V			0.36	.O	0.44		0.44	
	I _{OL} = 75 mA [†]	5.5 V				20	1.65		1.65	
lį	V _I = V _{CC} or GND	5.5 V			±0.1	D'A	±1		±1	μΑ
I _{OZ}	$V_O = V_{CC}$ or GND	5.5 V			±0.5	~	±5		±5	μΑ
ICC	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			8		80		80	μΑ
ΔI _{CC} ‡	One input at 3.4 V, Other inputs at V _{CC} or GND	5.5 V			0.9		1		1	mA
C _i	V _I = V _{CC} or GND	5.5 V		4						pF
Co	$V_O = V_{CC}$ or GND	5 V		13						pF

T Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	TO (OUTPUT)	T _A = 25°C			54ACT16541		74ACT16541		UNIT
PARAMETER	(INPUT)		MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
t _{PLH}	^	V	3.1	5.9	7.9	3.1	9	3.1	9	20
t _{PHL}	A	T	2.7	6.3	8.3	2.7	9.2	2.7	9.2	ns
^t PZH			2.8	6.5	8.9	2.8	9.7	2.8	9.7	ne
^t PZL	OE	Y	3.5	7.5	9.9	3.5	11	3.5	11	ns
^t PHZ	ŌĒ	V	4.5	8.5	10.3	4.5	11.3	4.5	11.3	ns
t _{PLZ}	OE .	l ^r	4.9	8	9.9	4.9	10.7	4.9	10.7	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

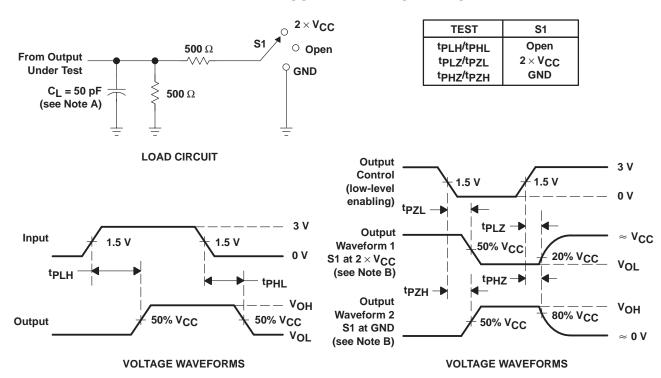
	PARAMETER	TEST CO	TYP	UNIT		
	Dower dissinction conscitance per huffer/driver	Outputs enabled	C _I = 50 pF,	f = 1 MHz	40	pF
Срс	Power dissipation capacitance per buffer/driver	Outputs disabled	CL = 50 pr,	I = I IVITIZ	9.5	



[‡] This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

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PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_I includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \Omega$, $t_f = 3$ ns, $t_f = 3$ ns.
- D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

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PACKAGING INFORMATION

Orderable part number	Status (1)	Material type	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
74ACT16541DL	Obsolete	Production	SSOP (DL) 48	-	-	Call TI	Call TI	-40 to 85	ACT16541
74ACT16541DLR	Active	Production	SSOP (DL) 48	1000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT16541
74ACT16541DLR.A	Active	Production	SSOP (DL) 48	1000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT16541

⁽¹⁾ Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

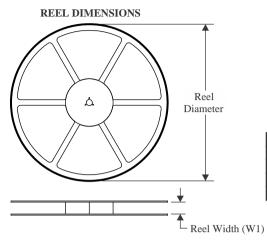
⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

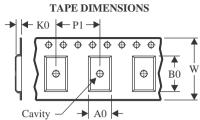
⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width						
В0	Dimension designed to accommodate the component length						
K0	0 Dimension designed to accommodate the component thickness						
W	Overall width of the carrier tape						
P1	Pitch between successive cavity centers						

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
74ACT16541DLR	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1

PACKAGE MATERIALS INFORMATION

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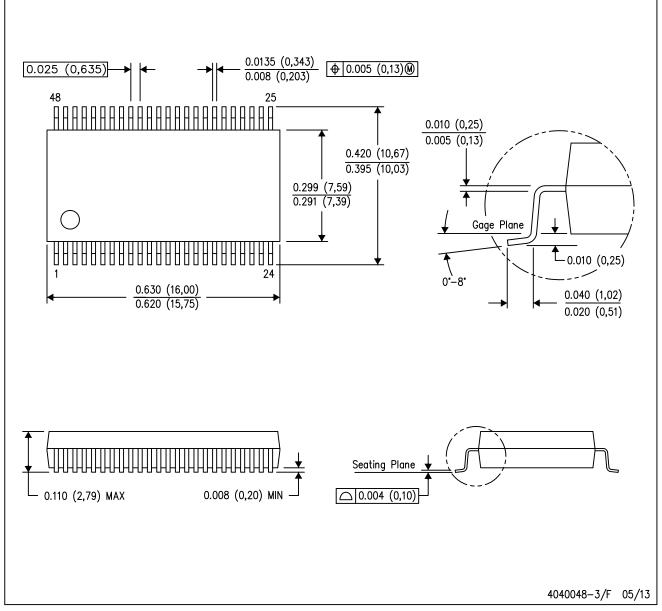


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
74ACT16541DLR	SSOP	DL	48	1000	356.0	356.0	53.0

DL (R-PDSO-G48)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MO-118

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